

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shinya Morita</td> <td>11/06/2012</td> </tr> <tr> <td>Koichi Ikeda</td> <td>11/06/2012</td> </tr> <tr> <td>Akira Akiba</td> <td>11/08/2012</td> </tr> <tr> <td>Mitsuo Hashimoto</td> <td>11/06/2012</td> </tr> </tbody> </table>		Name	Execution Date	Shinya Morita	11/06/2012	Koichi Ikeda	11/06/2012	Akira Akiba	11/08/2012	Mitsuo Hashimoto	11/06/2012
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>Sony Corporation</td> </tr> <tr> <td>Street Address:</td> <td>1-7-1 Konan, Minato-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	Sony Corporation	Street Address:	1-7-1 Konan, Minato-ku	City:	Tokyo	State/Country:	JAPAN		
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 3128767934  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 3128767925</p> <p>Email: patents@snrdenton.com</p> <p>Correspondent Name: SNR DENTON US LLP</p> <p>Address Line 1: P.O. BOX 061080</p> <p>Address Line 4: CHICAGO, ILLINOIS 60606-1080</p>											
ATTORNEY DOCKET NUMBER:	09792909-8886										
NAME OF SUBMITTER:	David R. Metzger										
	This document serves as an Oath/Declaration (37 CFR 1.63).										
<p>Total Attachments: 4</p> <p>source=SP339662US00_Dec-Assgmt#page1.tif</p> <p>source=SP339662US00_Dec-Assgmt#page2.tif</p> <p>source=SP339662US00_Dec-Assgmt#page3.tif</p> <p>source=SP339662US00_Dec-Assgmt#page4.tif</p>											

OP \$40.00 13688728

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

<b>Title of Invention</b>	<b>WAVEGUIDE, INTERPOSER SUBSTRATE INCLUDING THE SAME, MODULE, AND ELECTRONIC APPARATUS</b>
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As the below named inventor, I hereby declare that:

This declaration is directed to:

The attached application, or

United States application or PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, SONY CORPORATION, with offices at 1-7-1 KONAN, MINATO-KU, TOKYO, 108-0075, JAPAN (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: SHINYA MORITA Date: November 6, 2012

Signature: Shinya Morita

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LEGAL NAME OF INVENTOR	
Inventor: <u>KOICHI IKEDA</u>	Date: <u>November 6, 2012</u>
Signature: <u>Koichi Ikeda</u>	

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LEGAL NAME OF INVENTOR

Inventor: AKIRA AKIBA

Date: November 8, 2012

Signature: Akira Akiba

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LEGAL NAME OF INVENTOR	
Inventor: <u>MITSUO HASHIMOTO</u>	Date: <u>November 6, 2012</u>
Signature: <u>Mitsuo Hashimoto</u>	